

Date Created : 2007/11/19
Date Issued On : 2007/11/30
PCN# : Q4074701

FORECAST CHANGE NOTIFICATION

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A Final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

Technical Contact:

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PCN Originator:

Name: Sun, Brian
E-mail: Brian.Sun@fairchildsemi.com
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Implementation of change:

Expected 1st Device Shipment Date: 2008/02/29

Earliest Year/Work Week of Changed Product: 0810

Change Type Description: Mold Compound

Description of Change (From): 8LD TSSOP package assembly at all FSC approved manufacturing locations using non Green mold compound as shown in table 1.

Description of Change (To): 8LD TSSOP package assembly at all FSC approved manufacturing locations using Green mold compound as shown in table 2.

Reason for Change : Green initiative by Fairchild Semiconductor. Fairchild Semiconductor is dedicated to being a good corporate citizen. All Fairchild Semiconductor products are 2nd level interconnect lead-free and RoHS compliance. The referenced material changes have been made to provide a 'Full Green' (Halogen Free Flame Retardant) package. For additional details on the corporate wide green initiative please visit our Web site at :

<http://www.fairchildsemi.com/company/green/index.html> Manufacturing will occur at the same assembly facilities producing the current non-green products. Package outline drawings of the affected products remain un-changed. Green products will be fully compliant to all published data sheet specifications and will be interchangeable with current non-green product. Quality and reliability will remain at the highest standards already demonstrated with Fairchild's existing products.

Qual/REL Plan Numbers : Q20070466

Qualification :

To qualify KMC3510M green mold compound as a replacement for KMC184-7 at GEM for assembly of TSSOP package.

Change From

Table 1

Assembly Site	Gem Electronics
Package	TSSOP-8
Leadframe	C7025
Die Attach Material	84-1LM1SR4
Wire	2 mil Au
Mold Compound	KMC184-7
Lead Finish	Matte Sn

Change To

Table 2

Assembly Site	Gem Electronics
Package	TSSOP-8
Leadframe	C7025
Die Attach Material	84-1LM1SR4
Wire	2 mil Au
Mold Compound	KMC3510M
Lead Finish	Matte Sn

Qualification Stress Test and Sample Size Detail

Device #1	FDW2508PB
Package:	-1
#Leads:	-1

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

Stress	P/C	Standard	Conditions	Readpoints			Samples
				TP1	TP2	TP3	A
ACLV	X	JESD22-A102	100%RH, 121C	96			77
H3TRB	X	JESD22-A101B	85%RH, 85C, 80% of related BV	168	500	1000	77
HTGB		JESD22-A108	150C, 100% of related VgsV	168	500	1000	77
HTRB		JESD22-A108	150C, 80% of related BV	168	500	1000	77
PRCL		MIL-STD-750-1036	Delta 100C, 2 Min cycle	5000			77
TMCL1	X	JESD22-A104	-65C, 150C	100	500		77

Device #2	FDW254P
Package:	-1
#Leads:	-1

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A

PCNL1A		JESD22-A113			0
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Environment Stress Detail:

Stress	P/C	Standard	Conditions	Readpoints			Samples
				TP1	TP2	TP3	A
ACLV	X	JESD22-A102	100%RH, 121C	96			77
H3TRB	X	JESD22-A101B	85%RH, 85C, 80% of related BV	168	500	1000	77
HTGB		JESD22-A108	150C, 100% of related VgsV	168	500	1000	77
HTRB		JESD22-A108	150C, 80% of re- lated BV	168	500	1000	77
PRCL		MIL- STD-750-1036	Delta 100C, 2 Min cycle	5000			77
TMCL1	X	JESD22-A104	-65C, 150C	100	500		77

Device #3	FDW2601NZ
Package:	
#Leads:	

Precondition Description:

Stress	P/C	Standard	Conditions	Read- points	Sample
					A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

Stress	P/C	Standard	Conditions	Readpoints			Samples
				TP1	TP2	TP3	A
ACLV	X	JESD22-A102	100%RH, 121C	96			77
H3TRB	X	JESD22-A101B	85%RH, 85C, 80% of related BV	168	500	1000	77
HTGB		JESD22-A108	150C, 100% of related VgsV	168	500	1000	77
HTRB		JESD22-A108	150C, 80% of re- lated BV	168	500	1000	77
PRCL		MIL- STD-750-1036	Delta 100C, 2 Min cycle	5000			77
TMCL1	X	JESD22-A104	-65C, 150C	100	500		77

Product Id Description :

Affected FSIDs :

5ES4_B5E012A	FDW2501N	FDW2501NZ
FDW2501N_NBDE006A	FDW2502P	FDW2503N
FDW2503NZ	FDW2503N_NL	FDW2504P
FDW2506P	FDW2506P_NL	FDW2507N
FDW2507NZ_NL	FDW2508P	FDW2508PB
FDW2508P_NBCP007A	FDW2510NZ_NL	FDW2511NZ
FDW2511NZ_NL	FDW2512NZ	FDW2520C
FDW2521C	FDW2521C_NL	FDW252P
FDW254P	FDW254PZ	FDW254P_NL
FDW256P	FDW258P	FDW2601NZ
FDW262P	FDW6923	FDW9926A
FDW9926A_NL	FDW9926NZ	SI6426DQ
SI6435DQ	SI6466DQ	SI6933DQ

SI6955DQ		
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